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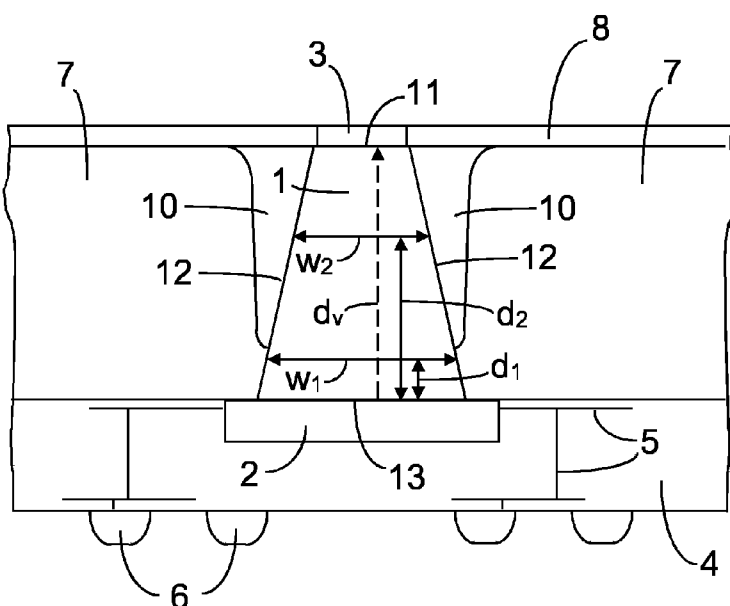


FIG 1

(57) Abstract: The lens assembly comprises a lens-shaped region (1) having an upper surface (11), a lateral surface (12) surrounding the lens-shaped region, and a bottom surface (13). An optoelectronic component (2) is arranged at or near the bottom surface, and an aperture (3) is arranged at the upper surface, so that the lens is arranged between the optoelectronic component and the aperture. Widths (w_1 , w_2) of the lens that are defined in a specified lateral direction decrease from a maximal width at or near the bottom surface to a non-vanishing minimal width at the upper surface. In particular, the entire lens may be tapered. Significant figure: Figure

Description

LENS ASSEMBLY, OPTOELECTRONIC PACKAGE AND METHOD OF PRODUCING
AN OPTOELECTRONIC PACKAGE WITH LENS ASSEMBLY

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Ambient light sensors (ALS) are commonly used to control the
brightness of displays, both for user comfort and for the
purpose of conserving battery power in handheld devices.

Customers would like the ALS to respond to light hitting the
10 sensor aperture from a wide range of angles. At the same
time, many optical sensors are prone to error when light
impacts the sensor surface at large angles.

US 2007/0176081 A1 discloses a lens assembly for use with an
15 ambient light sensor. The lens is arranged in an aperture of
a housing to direct incident light over an area of the light
sensor that is greater than the area of the housing aperture.

US 8,319,764 B2 discloses an ambient light sensor used for a
20 dynamical adjustment of display brightness to compensate for
changes in ambient light. A wave guide is provided for
improving angular response.

US 8,378,577 B2 discloses a liquid crystal display including
25 an electronically controlled backlight module and an ambient
light sensor, which comprises a photosensitive unit and an
optical sheet with a plurality of V-shaped micro structures.

US 2014/0103816 A1 discloses an arrangement of a touchscreen
30 glass for increasing the reception of an ambient light sensor
of a mobile phone. A light uniformizing film is disposed
between the touchscreen glass and an optical sensor.

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It is an object of the present invention to disclose a compact optoelectronic package providing a wide field of view. It is a further object to disclose a method of producing the optoelectronic package.

5 This object is achieved with the lens assembly according to claim 1, with the optoelectronic package according to claim 11, and with the method of producing an optoelectronic package according to claim 12. Embodiments and variants derive from the dependent claims.

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The lens assembly comprises a lens or lens-shaped region, which has an upper surface, a lateral surface surrounding the lens or lens-shaped region, and a bottom surface. An optoelectronic component is arranged at or near the bottom
15 surface, and an aperture is arranged at the upper surface, so that the lens or lens-shaped region is arranged between the optoelectronic component and the aperture. If a direction pointing from the bottom surface towards the upper surface is designated as vertical direction, and one of the directions
20 that are orthogonal to the vertical direction is specified as the relevant lateral direction, widths of the lens or lens-shaped region are defined in this lateral direction by the lateral surface. These widths decrease in the vertical direction from a maximal width at or near the bottom surface
25 to a non-vanishing minimal width at the upper surface.

An embodiment of the lens assembly further comprises an opaque encasement arranged at or near at least a portion of the lateral surface.

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A further embodiment of the lens assembly comprises an encasement forming the lateral surface, and the lateral

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surface is reflective for radiation incident from within the lens or lens-shaped region.

5 In a further embodiment of the lens assembly, an encasement is arranged adjacent to at least a portion of the lateral surface, and the encasement has an index of refraction that is smaller than the index of refraction of the lens or lens-shaped region.

10 In a further embodiment of the lens assembly, the entire lens or lens-shaped region is tapered towards the aperture. This means that the widths of the lens or lens-shaped region that are measured in the same lateral direction decrease from a maximal width at the bottom surface of the lens or lens-
15 shaped region to a non-vanishing minimal width at the upper surface of the lens or lens-shaped region, and this is true for any specified lateral direction.

In a further embodiment of the lens assembly, the lens or
20 lens-shaped region is not axially symmetrical.

A further embodiment of the lens assembly comprises a dimple in the upper surface of the lens or lens-shaped region.

25 In a further embodiment of the lens assembly, areas of the lateral surface of the lens or lens-shaped region join at boundaries where the inclination of the lateral surface with respect to the bottom surface is discontinuous.

30 In a further embodiment of the lens assembly, the optoelectronic component is an ambient light sensor.

In a further embodiment of the lens assembly, an array of lenses or lens-shaped regions is provided for the optoelectronic component, the lens or lens-shaped region forming part of the array. The lenses or lens-shaped regions may all be tapered and may in particular have the same shape. An array of tapered lenses or lens-shaped regions may especially be favourable if the optoelectronic component comprises an array of optoelectronic devices like photosensors, for example.

The optoelectronic package including such a lens assembly comprises a carrier including electric interconnections. The optoelectronic component may be mounted on the carrier or integrated in the carrier.

In an embodiment of the optoelectronic package, the carrier is a semiconductor substrate or wafer, and the optoelectronic component is integrated in the semiconductor substrate or wafer.

In a further embodiment of the optoelectronic package, the carrier is a printed circuit board, and the optoelectronic component is mounted on the printed circuit board.

The method of producing an optoelectronic package comprises providing a carrier including electric interconnections, arranging an optoelectronic component in or on the carrier, forming a lens or lens-shaped region or an array of lenses or lens-shaped regions and an encasement of the lens or lens-shaped region or of the array on or above the optoelectronic component, and forming an aperture of the encasement opposite the optoelectronic component. The aperture may especially be formed in a cap layer, which is mounted to the encasement.

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In a variant of the method, the encasement and the lens or lens-shaped region or the array are formed from different materials by moulding.

- 5 In a further variant, a coating is applied to the lens or lens-shaped region after moulding. Then the encasement is formed on the carrier adjacent to the coating by moulding, and the coating is subsequently removed, thus forming a void.
- 10 In a further variant, a lateral surface of the lens or lens-shaped region or of the array is formed by a reflective surface of the encasement.

The following is a detailed description of examples of the lens assembly and the method of producing an optoelectronic package in conjunction with the appended figures.

Figure 1 is a cross section of an optoelectronic package including a lens assembly.

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Figure 2 is a cross section of a further optoelectronic package including a lens assembly.

Figure 3 is a cross section of a further optoelectronic package including a tapered lens with convex sidewall.

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Figure 4 is a cross section of a further optoelectronic package including a tapered lens with concave sidewall.

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Figure 5 is a cross section of a further lens assembly including a lens having different bevels.

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Figure 6 is a top view of an optoelectronic package including a lens assembly.

5 Figure 7 is a top view of a further optoelectronic package including a lens assembly.

Figure 8 is a top view of an optoelectronic package including a lens assembly forming an array.

10 Figure 9 is a top view of a further optoelectronic package including a lens assembly forming an array.

Figure 10 is a perspective view of a lens assembly including a moulded lens.

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Figure 11 is a perspective view according to Figure 10 with an encasement arranged for mounting.

20 Figure 12 is a perspective view according to Figure 10 after the lens has been embedded in a coating.

Figure 13 is a perspective view of the shape of an encasement as it is moulded on the carrier.

25 Figure 14 is a perspective view of an optoelectronic package comprising the lens assembly and the encasement.

30 The dimensions shown in the figures are not drawn to scale, and some aspect ratios may have been exaggerated for the sake of clarity.

Figure 1 is a cross section of an optoelectronic package including a lens assembly. A lens 1 formed from a transparent

material or a lens-shaped region 1, which is limited by boundary surfaces, is arranged above an optoelectronic component 2, which may be a photodetector, for instance, or a device emitting radiation. The optoelectronic component 2 may especially be provided as an ambient light sensor, but other applications may be suitable as well. A surface of the lens or lens-shaped region 1 facing the optoelectronic component 2, which will here be designated as the bottom surface 13, may be contiguous with a surface of the optoelectronic component 2. The lens or lens-shaped region 1 may instead be arranged at a distance from the optoelectronic component 2, which may be embedded in transparent material filling the interspace between the optoelectronic component 2 and the lens or lens-shaped region 1. At least one further optical component like an interference filter, for instance, may optionally be arranged at or on the optoelectronic component 2. Figure 1 shows a schematic representation of the optoelectronic component 2, which is meant to include these options. An aperture 3 is arranged at the upper surface 11 of the lens or lens-shaped region 1 opposite the bottom surface 13. The lens or lens-shaped region 1 is thus arranged between the optoelectronic component 2 and the aperture 3.

The optoelectronic package comprising the lens assembly may include a carrier 4 with electric interconnections 5, which may be provided with bump contacts 6 or the like for external electric connection. The carrier 4 may be a semiconductor substrate or wafer, and the optoelectronic component 2 may be integrated in the semiconductor substrate or wafer. In this case the interconnections 5 may form a wiring, which may also be provided for further integrated components like CMOS components, and may in particular include through-substrate vias. The interconnections 5 and integrated components may be

produced in a standard CMOS process, for instance. The lens or lens-shaped region 1 and the aperture 3 may thus be integrated at wafer level, which enables minimizing the footprint and assembly costs. The carrier 4 may instead be any other carrier suitable for optoelectronic packages, like a printed circuit board, for instance. The optoelectronic component 2 may be mounted on the printed circuit board using conventional semiconductor technology.

An encasement 7 may be provided for the lens or lens-shaped region 1. The encasement 7 may be opaque, or it may be transparent, in particular comprising an index of refraction that allows total internal reflection in the lens or lens-shaped region 1. If the lens assembly comprises a lens 1

formed from a transparent material, the encasement 7 may be in contact with the entire lateral surface 12 of the lens 1, or the encasement 7 may only be contiguous with a portion of the lateral surface 12 of the lens 1, as shown in Figure 1.

The encasement 7 may instead be arranged at a distance from the lens 1. If the encasement 7 does not cover the entire

lateral surface 12 of the lens 1, a void 10, which may be filled with air, for instance, is left between the encasement 7 and the lens 1. In particular, if the encasement 7 is opaque, such a void 10 of small index of refraction may

enable the occurrence of total internal reflection in the

lens 1. The lens 1 and/or the encasement 7 can be formed by moulding, for example.

A lens-shaped region 1 may be present instead of a lens 1.

The lens-shaped region 1, which may be filled with air, for

instance, can be defined by the encasement 7, which in this

case provides the lateral surface 12 of the lens-shaped

region 1. Furthermore, any other suitable surface reflecting the radiation or providing a discontinuity of the index of

refraction may be provided between regions of the package. In particular, the lateral surface 12 of the lens-shaped region 1 may be provided with a reflective coating, which is not shown in Figure 1. Surface layers that reflect the incident radiation, like aluminium coatings on plastic or glass, which may be used as the material of the encasement 7, for instance, may also be applied to fold the path of radiation.

The aperture 3 can be formed by the encasement 7, or an optional cap layer 8 with a window provided to form the aperture 3 can be mounted to the lens assembly. The cap layer 8 may be opaque or semitransparent to shield stray light, and its transparency may especially depend on the wavelength. In particular, the cap layer 8 may be formed by a metal shield, for instance.

A direction pointing from the bottom surface 13 towards the upper surface 11 will here be designated as vertical direction d_v , and one of the directions that are orthogonal to the vertical direction d_v is specified as the relevant lateral direction. Widths w_1 , w_2 of the lens or lens-shaped region 1 are defined in the specified lateral direction by the lateral surface 12. Figure 1 shows a first width w_1 at a first distance d_1 from the bottom surface 13 and a smaller second width w_2 at a larger second distance d_2 from the bottom surface 13. The widths w_1 , w_2 thus defined decrease in the vertical direction d_v from a maximal width at the bottom surface 13 to a non-vanishing minimal width at the upper surface 11. In the embodiment shown in Figure 1, the lens or lens-shaped region 1 especially comprises the shape of a truncated cone. Other suitable shapes will be described in the following in conjunction with various embodiments.

Figure 2 is a cross section of a further optoelectronic package including a lens assembly. Components of the optoelectronic package according to Figure 2 that correspond to similar components of the optoelectronic package according to Figure 1 are designated with the same reference numerals. The aperture 3 of the lens assembly shown in Figure 2 is formed by the encasement 7, which covers the entire lateral surface 12 of the lens or lens-shaped region 1 in this embodiment. The lens or lens-shaped region 1 can be used to direct incident radiation from a wide field of view onto the optoelectronic component 2. In the following description, the lens assembly will be assumed to include a lens 1 formed from a transparent material having an index of refraction larger than the index of refraction of air (≈ 1).

Figure 2 shows a ray 9 incident on the upper surface 11 of the lens 1 through the aperture 3 at an angle a_1 of incidence with respect to the normal n_1 to the upper surface 11. The angle a_2 of refraction differs from the angle a_1 of incidence according to Snell's law, taking account of the index of refraction of the lens 1. The direction of the ray 9 thus deviates within the lens 1 from the direction of a virtual straight ray 9'. The refracted ray 9 reaches the lateral surface 12 of the lens 1 at a further angle a_3 of incidence with respect to the normal n_2 to the lateral surface 12. If the index of refraction of the encasement 7 is smaller than the index of refraction of the lens 1 and the further angle a_3 of incidence is sufficiently large, the ray 9 is reflected by total internal reflection at the lateral surface 12 of the lens 1. The angle a_3' of reflection is the same as the further angle a_3 of incidence, and the ray 9 is thus ultimately directed onto the optoelectronic component 2. The original inclination of the ray 9 with respect to the normal

n_1 is thus decreased, and the field of view of the optoelectronic component 2 is enlarged. The direction of the ray 9 may be reversed, if the optoelectronic component 2 is a light-emitting device, for example.

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Figure 3 is a cross section of a further optoelectronic package including a lens assembly. Components of the optoelectronic package according to Figure 3 that correspond to similar components of the optoelectronic package according to Figures 1 and 2 are designated with the same reference numerals. The lens assembly of the embodiment according to Figure 3 comprises a tapered lens 1 with a convex cross section of the lateral surface 12. The lateral surface 12 is bulged in such a manner that its inclination with respect to the bottom surface 13 decreases in the vertical direction with increasing distance from the bottom surface 13. This means that, if the cross section shown in Figure 3 is at a position where the lateral surface 12 is orthogonal to the plane of the drawing, so that the normal n_2 to the lateral surface 12 always lies within the cross section, the acute angle between the normal n_3 to the bottom surface 13 and the normal n_2 to the lateral surface 12 at a given point p of the lateral surface 12 decreases with increasing distance of the point p from the bottom surface 13. The shape of the lateral surface 12 may be selected from a variety of shapes, and its curvature can be adapted to requirements of individual applications. The curvature may be elliptical, parabolical, hyperbolical or exponential, for instance, or corresponding to any other either analytically defined or irregular geometrical shapes.

The upper surface 11 and the portion of the lateral surface 12 that is in the vicinity of the upper surface 11 may show a

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pronounced deviation from the general shape of the lateral surface 12. In particular, the top of the lens 1, where radiation enters or leaves the lens 1, may be spherical, ellipsoidal or the like, irrespective of the shape of the lower portion of the lateral surface 12.

The height of the lens 1 and its tapering may be restricted by prescribed maximal dimensions of the package and the physical width of the active area, which may cause deviations from the desired angular field of view. Such deviations can at least partially be corrected by a dimple 18 formed in the upper surface 11 of the lens 1. Such a dimple 18 is suitable for manufacture by moulding, which may be preferred in view of efficiency and low costs. In particular, the size of the dimple 18 and its curvature comply with requirements specified by mould manufacturers. Instead of the dimple 18, an opaque or partially opaque (i. e. translucent) ink dot placed on the tip of the lens 1 may be applied as an alternative for attenuating the radiation in the vicinity of the axis of the lens 1.

Figure 4 is a cross section of a further optoelectronic package including a lens assembly. Components of the optoelectronic package according to Figure 4 that correspond to similar components of the optoelectronic package according to Figure 3 are designated with the same reference numerals. The lens assembly of the embodiment according to Figure 4 comprises a tapered lens 1 with a concave cross section of the lateral surface 12. The lateral surface 12 is curved in such a manner that its inclination with respect to the bottom surface 13 increases in the vertical direction with increasing distance from the bottom surface 13. This means that, if the cross section shown in Figure 4 is at a position

where the lateral surface 12 is orthogonal to the plane of the drawing, so that the normal n_2 to the lateral surface 12 always lies within the cross section, the acute angle between the normal n_3 to the bottom surface 13 and the normal n_2 to the lateral surface 12 at a given point p of the lateral surface 12 increases with increasing distance of the point p from the bottom surface 13.

In the embodiment according to Figure 4, as in the embodiment according to Figure 3, the shape of the lateral surface 12 may be selected from a variety of shapes, and its curvature can be adapted to requirements of individual applications. The curvature may be elliptical, parabolical, hyperbolical or exponential, for instance, or corresponding to any other either analytically defined or irregular geometrical shapes. In other embodiments of the lens 1, the vertical curvature may be partially convex and partially concave.

In Figures 3 and 4 the curvature of the lateral surface 12 is clearly indicated. But in preferred embodiments of the lens assembly, the vertical curvature of the lens 1 may typically be weaker than shown in the figures, so that the shape of the lateral surface 12 does not deviate significantly from a cone. The top of the lens 1 including the upper surface 11 may deviate from the general shape of the lens 1 and may especially be spherical or ellipsoidal, irrespective of the shape of the lower portion of the lateral surface 12.

If the height of the lens 1 and its tapering is restricted by prescribed requirements, a dimple 18 can be provided in the upper surface 11 of the lens 1 as described above in conjunction with the embodiment according to Figure 3. Such a dimple 18 can also be provided in the upper surface 11 of the

lens 1 of any other embodiment, in particular in the upper surface 11 of a lens 1 forming a truncated cone, as in the embodiments according to Figures 1 and 2.

5 Figure 5 is a cross section of a further lens assembly including a lens having different bevels. The lateral surface 12 is formed by lateral surface areas 14, 15, 16 of different inclinations. These lateral surface areas 14, 15, 16 may have any shape that is compatible with the general tapering of the
10 lens 1, in particular a vertical convex or concave curvature. In Figure 5, by way of example, the lateral surface areas 14, 15, 16 are shown to be truncated cones of different opening angles. The angles a_4 , a_5 , a_6 of inclination of the lateral surface areas 14, 15, 16 with respect to the bottom surface
15 13 are shown in Figure 5 by means of broken lines extending the cross sections of the upper lateral surface area 14 and the middle lateral surface area 15. The angle a_4 of inclination of the upper lateral surface area 14 is smaller than the angle a_5 of inclination of the middle lateral
20 surface area 15, and the latter angle a_5 is smaller than the angle a_6 of inclination of the lower lateral surface area 16. The lateral surface areas 14, 15, 16 join at boundaries 17 where the angles a_4 , a_5 , a_6 of inclination vary discontinuously.

25

Figure 5 shows how a convex lens 1, especially a lens 1 having different bevels, may be used for the direction of a ray 9 by means of repeated total internal reflection. The incident ray 9 is refracted at the upper surface 11 of the
30 lens 1 and totally internally reflected at the upper lateral surface area 14. As the upper lateral surface area 14 and the middle lateral surface area 15 comprise normals n_4 , n_5 that are not parallel to one another, the reflected ray 9 may

impinge on the middle lateral surface area 15 and again be reflected by total internal reflection. As the middle lateral surface area 15 and the lower lateral surface area 16 comprise normals n_5 , n_6 that are not parallel either, the twice reflected ray 9 may also impinge on the lower lateral surface area 16 and again be reflected by total internal reflection. The total angle of deflection of the ray 9 thus achieved is essentially larger than the angle of deflection in the case of only one total internal reflection. Figure 5 also shows how the succession of different angles a_4 , a_5 , a_6 of inclination of the lateral surface 12 causes a corresponding succession of angles of incidence sufficiently large for total internal reflection of the ray 9.

Figure 6 is a top view of an optoelectronic package including a lens assembly. The optoelectronic component 2 is arranged on or in the carrier 4, and the lens or lens-shaped region 1 is arranged on or above the optoelectronic component 2. The upper surface 11 of the lens or lens-shaped region 1 is shown to be provided with a dimple 18. In the embodiment shown in Figure 6, the lateral surface 12 of the lens or lens-shaped region 1 is axially symmetrical. The width of the lens or lens-shaped region 1 therefore only depends on the height above the optoelectronic component 2, but not on the lateral direction d_{lat} . The width of the lens or lens-shaped region 1 decreases from a maximal width w_{max} at the bottom surface 13 to a non-vanishing minimal width w_{min} at the upper surface 11.

In this description and in the claims, a width of the lens or lens-shaped region 1 is always meant to be defined by the lateral surface 12 of the lens or lens-shaped region 1. If the upper surface 11 of the lens or lens-shaped region 1 is not flat, the maximal distance from the bottom surface 13 may

be reached at the centre of the upper surface 11 or, if a dimple 18 is present, on a circle around the centre of the upper surface 11. In this case a width of the lens or lens-shaped region 1 is not to be measured between points lying
5 within the upper surface 11. Hence the relevant minimal width $w_{\min}$ shown in Figure 6 does not vary if a lateral dimension of the top of the lens or lens-shaped region 1 varies owing to a curvature of the upper surface 11 in the region above the lateral surface 12. In this sense the width of the lens or
10 lens-shaped region 1 is non-vanishing, even if the upper surface 11 may have a central peak. Whereas the lateral width of a conical lens vanishes at the apex, the lateral width of the lens or lens-shaped region 1 used in the lens assembly does not vanish, which makes a substantial difference.

15 Figure 7 is a top view of a further optoelectronic package including a lens assembly. The components shown in Figure 7 that correspond to components shown in Figure 6 are designated with the same reference numerals. In the
20 embodiment shown in Figure 7, the lens or lens-shaped region 1 is not axially symmetrical. This may be desired if the field of view is not intended to be axially symmetrical either. The lens or lens-shaped region 1 may be a truncated elliptical cone, for example. The lateral surface 12 may
25 instead be convex or concave or composed of surface areas providing discontinuous inclinations as described above. The lateral width measured in any fixed lateral direction decreases in the vertical direction from a maximal width at the bottom surface 13 to a non-vanishing minimal width at the
30 upper surface 11.

In the embodiment according to Figure 7, the bottom surface 13 is an ellipse. In the case of a lens or lens-shaped region

1 forming an elliptical cone, at any fixed distance from the bottom surface 13, there is a lateral direction d_{lat} of smallest width of the lens or lens-shaped region 1 and a lateral direction D_{lat} of largest width of the lens or lens-shaped region 1, the directions corresponding to the major and minor axes of the ellipse. The lateral width measured in the lateral direction d_{lat} of smallest width of the lens or lens-shaped region 1 decreases from a maximal width w_{max} at the bottom surface 13 to a non-vanishing minimal width w_{min} at the upper surface 11. In the same way, the lateral width measured in the lateral direction D_{lat} of largest width of the lens or lens-shaped region 1 decreases from a maximal width W_{max} at the bottom surface 13 to a non-vanishing minimal width W_{min} at the upper surface 11.

Figure 8 shows a top view of an embodiment of the lens assembly comprising an array 19 of lenses or lens-shaped regions 1. A plurality of tapered lenses or lens-shaped regions 1 forming an array may thus be employed to cover a large optoelectronic component 2 or an array of optoelectronic components 2, especially if there are constraints on the height of the package. A tapered lens or lens-shaped region 1 can be arranged above each optoelectronic component 2 of an array of optoelectronic components 2, as shown in Figure 8. Instead, groups of optoelectronic components 2 can be provided with one lens or lens-shaped region 1 of the array 19. A plurality of individual apertures 3 forming an array of apertures may be adapted to the upper surfaces 11 of the lenses or lens-shaped regions 1 to prevent radiation from entering the lenses or lens-shaped regions 1 through the lateral surface 12.

Figure 9 shows a top view of a further embodiment comprising an array 19 of lenses or lens-shaped regions 1. In the embodiment according to Figure 9, the array 19 of lenses or lens-shaped regions 1 is provided for one large optoelectronic component 2. In an array of optoelectronic components 2, each optoelectronic component 2 or some of the optoelectronic components 2 may be provided with an array 19 of lenses or lens-shaped regions 1 as shown in Figure 9. The array 19 of lenses can be provided with a corresponding array of individual apertures 3, in order to prevent radiation from entering the lenses or lens-shaped regions 1 through their lateral surfaces 12.

Figure 10 is a perspective view of a lens assembly including a moulded lens. The lens 1 is mounted on a carrier 4 above the optoelectronic component 2, which may be integrated in the carrier 4, for example. In the embodiment according to Figure 10, a bottom portion of the lens 1 has a concave vertical curvature, while the upper portion has a convex vertical curvature. Instead, a bottom portion of the lens 1 may have the shape of a truncated cone, while the upper portion forms a paraboloid of revolution, for example. Other shapes of the lens 1, especially the shapes shown in Figures 1 to 5, may also be formed by moulding. Figure 10 shows the upper surface 11 of the lens 1 to be flat, but the top of the lens 1 may instead be curved, so that moulding is facilitated. The top of the lens 1 may especially be provided with a dimple as in the embodiments previously described. If the lens 1 is formed by moulding, a mould may be applied directly on the carrier 4, and a mould compound that is intended as the material forming the lens 1 is then filled through a runner or sprue. A sprue ridge 20 may therefore

remain at the flank of the moulded lens 1, as shown in Figure 10 by way of example.

Figure 11 is a perspective view according to Figure 10 after
5 a partial removal of the sprue ridge 20, which may be effected by sawing, for example. A complete removal of the sprue ridge 20 may be preferred, but stubs 21 of the sprue ridge 20 may be left at the lateral surface 12 of the lens 1. An encasement 7 is prepared and arranged above the carrier 4
10 for mounting, as shown in Figure 11. The encasement 7 is provided with a recess 22 in the shape of the lens 1. Such an encasement 7 can also be formed by moulding, in particular using an opaque material suitable to shield the intended radiation. As indicated in Figure 11 by arrows, the
15 encasement 7 is put over the lens 1 and fastened on the carrier 4 by means of a suitable adhesive, for instance. A cover 8 as shown in Figure 1 may additionally be applied on the encasement 7.

20 Figure 12 is a perspective view according to Figure 10 for an intermediate product of a variant of the method. The lens 1 has been embedded in a coating 23, which is provided as a sacrificial layer. The coating 23 can be applied by conventional dispensing or moulding, for instance. The
25 lateral surface 12 of the lens 1 is preferably completely covered by the coating 23. Apart from that, the coating 23 may have any appropriate shape. The upper surface 11 may also be covered, or it may be free from the coating 23 as shown in Figure 12. The encasement 7 may subsequently be moulded
30 directly on the carrier 4 and the coating 23, which protects the lens 1. Only the tip of the lens 1 remains exposed, and thus the aperture 3 is formed. An opaque mold compound may be preferred for the encasement 7. The resulting structure is

similar to the result of the method previously described, but a glueing step for mounting the encasement 7 is avoided.

Figure 13 is a perspective view of the shape the encasement 7 takes when it is moulded on the carrier 4 comprising the lens 1 and the coating 23 according to Figure 12.

Figure 14 is a perspective view of an optoelectronic package comprising the lens assembly and the encasement 7 for the embodiment according to Figures 12 and 13. If the coating 23

comprises a material that can be removed by a suitable solvent, which does not attack the material of the lens 1, such a solvent may be applied to the exposed top surface of the coating 23, after the encasement 7 has been moulded, in order to remove the coating 23 and to form a void 10 between the lens 1 and the encasement 7. The resulting structure is similar to the embodiments shown in Figures 1, 3 and 4. Bump contacts 6, which may be solder balls, for instance, can be applied on the rear side of the carrier 4 for external electric connections.

Instead of the described method, both the transparent mould compound provided for the lens 1 and the preferably opaque mould compound provided for the encasement 7 may directly be applied onto the carrier 4, without use of a sacrificial layer like the coating 23 described above. Furthermore, by using an appropriate mould for the encasement 7, the lateral surface 12 of the lens 1 can be kept at least partially free from the mould compound of the encasement 7. A structure of the void 10 typically resembling the void 10 shown in the cross section of Figure 1, by way of example, may thus be obtained. An interference filter may favourably be applied to the optoelectronic component 2 to compensate for effects

caused by such a void 10 being present at an area of the lateral surface 12 of the lens 1.

The lens assembly may especially be provided by reflective surfaces to fold the path of the radiation, thus allowing the optical system to reside in a compact package, while still presenting a wide field of view. Nested structures multiply folding the light paths by reflection or refraction may also be applied to reduce the required dimensions of the package. Steep surfaces that reflect most of the light using Fresnel reflection, where the light travels from a low index medium (like air, for instance) to a higher index medium (like glass or transparent or semitransparent plastic, for instance) may be particularly favourable for the described purposes. The efficiency of the Fresnel reflection increases as the light strikes the surface at progressively steeper glancing angles.

The accuracy and efficiency of an optoelectronic device is enhanced by the described lens assembly. It provides a large field of view while restricting the angle of view presented to the optoelectronic component. A further benefit for the user will be the small aperture, which will be less visible than in conventional optoelectronic packages. The dimensions, especially the height, of the optoelectronic package using the described lens assembly are substantially reduced compared with conventional packages of ambient light sensors or the like. The use of an opaque mould or a metal shield as a cover eliminates the need for a rubber boot. The method of producing the lens assembly by moulding is appropriate for mass production and reduction of the manufacturing costs.

List of reference numerals

	1	lens or lens-shaped region
	2	optoelectronic component
5	3	aperture
	4	carrier
	5	interconnection
	6	bump contact
	7	encasement
10	8	cap layer
	9	ray
	9'	virtual ray
	10	void
	11	upper surface
15	12	lateral surface
	13	bottom surface
	14	upper lateral surface area
	15	middle lateral surface area
	16	lower lateral surface area
20	17	boundary
	18	dimple
	19	array of lenses
	20	sprue ridge
	21	stub
25	22	recess
	23	coating
	a ₁	angle of incidence
	a ₂	angle of refraction
	a ₃	further angle of incidence
30	a ₃ '	angle of reflection
	a ₄	angle of inclination of the upper lateral surface area
	a ₅	angle of inclination of the middle lateral surface area
	a ₆	angle of inclination of the lower lateral surface area

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	d_1	first distance
	d_2	second distance
	d_{lat}	lateral direction of smallest widths
	D_{lat}	lateral direction of largest widths
5	d_v	vertical direction
	n_1	normal to the upper surface
	n_2	normal to the lateral surface
	n_3	normal to the bottom surface
	n_4	normal to the upper lateral surface area
10	n_5	normal to the middle lateral surface area
	n_6	normal to the lower lateral surface area
	w_1	first width
	w_2	second width
	w_{max}	smallest maximal width
15	W_{max}	largest maximal width
	w_{min}	smallest minimal width
	W_{min}	largest minimal width

Claims

1. A lens assembly, comprising:
 - a lens or lens-shaped region (1), which has an upper surface (11), a lateral surface (12) surrounding the lens or lens-shaped region (1), and a bottom surface (13),
 - a lateral direction (d_{lat} , D_{lat}), which is orthogonal to a vertical direction (d_v) pointing from the bottom surface (13) towards the upper surface (11),
 - 10 - an optoelectronic component (2) arranged at or near the bottom surface (13), and
 - an aperture (3) at the upper surface (11), the lens or lens-shaped region (1) being arranged between the optoelectronic component (2) and the aperture (3),
 - 15 characterized in that
 - widths (w_1 , w_2) of the lens or lens-shaped region (1) that are defined in the lateral direction (d_{lat} , D_{lat}) by the lateral surface (12) decrease in the vertical direction (d_v) from a maximal width (w_{max} , W_{max}) at or near the bottom surface (13) to a non-vanishing minimal width (w_{min} , W_{min}) at the upper surface (11).
2. The lens assembly of claim 1, further comprising:
 - an opaque encasement (7) arranged at or near at least a
 - 25 portion of the lateral surface (12).
3. The lens assembly of claim 1, further comprising:
 - an encasement (7) forming the lateral surface (12), and
 - the lateral surface (12) being reflective for radiation
 - 30 incident from within the lens or lens-shaped region (1).
4. The lens assembly of claim 1, further comprising:
 - an index of refraction of the lens or lens-shaped region

(1), and
an encasement (7) having a smaller index of refraction
being arranged adjacent to at least a portion of the
lateral surface (12).

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5. The lens assembly of one of claims 1 to 4, wherein
the entire lens or lens-shaped region (1) is tapered
towards the aperture (3).

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6. The lens assembly of one of claims 1 to 5, wherein
the lens or lens-shaped region (1) is not axially
symmetrical.

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7. The lens assembly of one of claims 1 to 6, further
comprising:
a dimple (18) formed in the upper surface (11).

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8. The lens assembly of one of claims 1 to 7, wherein areas
(14, 15, 16) of the lateral surface (12) of the lens or
lens-shaped region (1) join at boundaries (17) where an
inclination (a_4 , a_5 , a_6) of the lateral surface (12) with
respect to the bottom surface (13) is discontinuous.

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9. The lens assembly of one of claims 1 to 8, wherein the
optoelectronic component (2) is an ambient light sensor.

30

10. The lens assembly of one of claims 1 to 9, further
comprising:
an array (19) of lenses or lens-shaped regions provided
for the optoelectronic component (2), the lens or lens-
shaped region (1) forming part of the array (19).

11. An optoelectronic package including a lens assembly of one of claims 1 to 10, comprising:

a carrier (4) including electric interconnections (5),
the optoelectronic component (2) being mounted on the
carrier (4) or integrated in the carrier (4).

12. A method of producing an optoelectronic package,
comprising:

- providing a carrier (4) including electric
interconnections (5),
- arranging an optoelectronic component (2) in or on the
carrier (4),
- forming a lens or lens-shaped region (1) or an array (19)
of lenses or lens-shaped regions and an encasement (7) of
the lens or lens-shaped region (1) or of the array (19)
on or above the optoelectronic component (2), and
- forming an aperture (3) of the encasement (7) opposite
the optoelectronic component (2).

13. The method of producing an optoelectronic package
according to claim 12, further comprising:
forming the encasement (7) and the lens or lens-shaped
region (1) or the array (19) from different materials by
moulding.

14. The method of producing an optoelectronic package
according to claim 13, further comprising:
after moulding the lens or lens-shaped region (1),
applying a coating (23),
moulding the encasement (7) on the carrier (4) adjacent
to the coating (23), and
subsequently removing the coating (23), thus forming a
void (10).

15. The method of producing an optoelectronic package according to one of claims 12 to 14, further comprising: forming a lateral surface (12) of the lens or lens-shaped region (1) or of the array (19) by a reflective surface of the encasement (7).
- 5

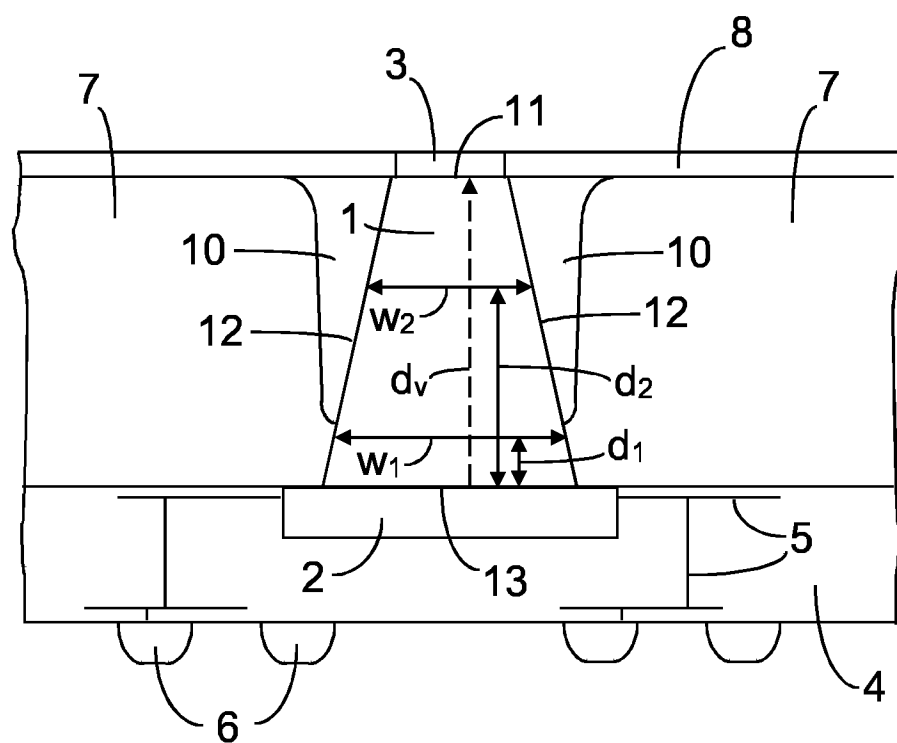


FIG 1

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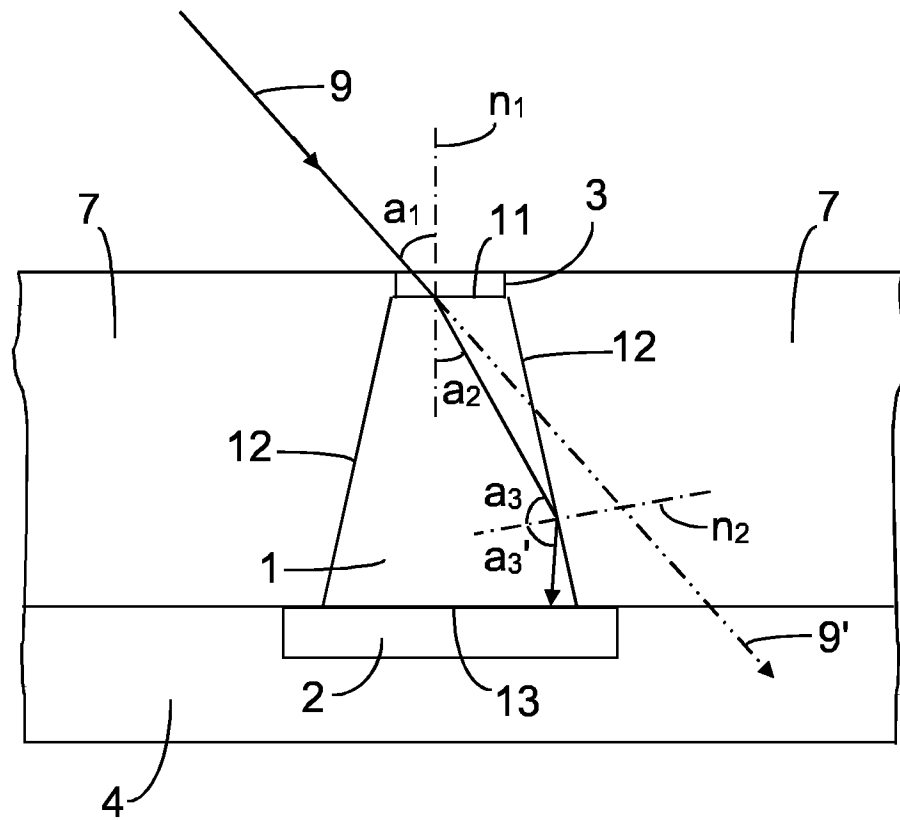


FIG 2

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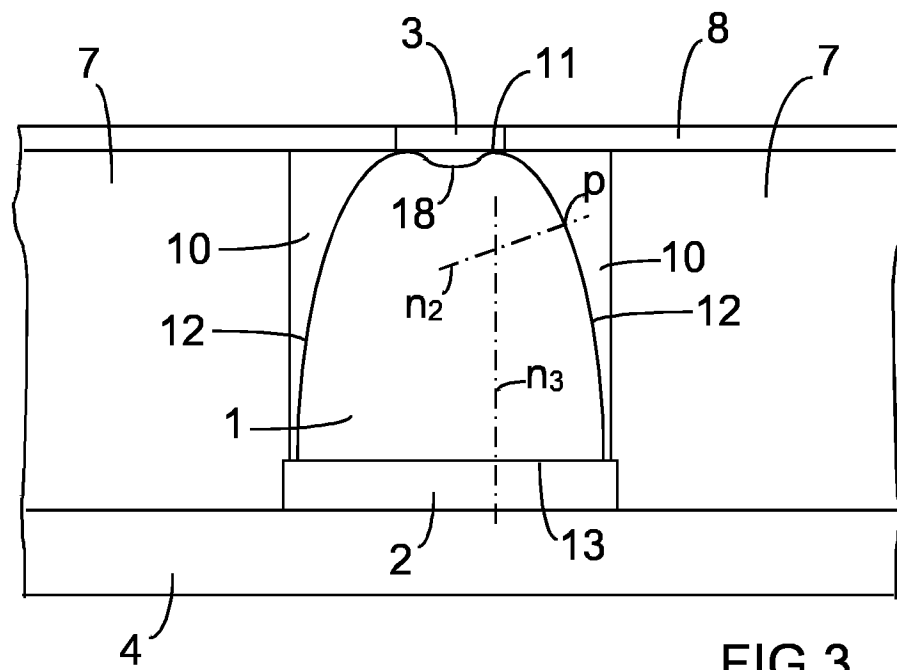


FIG 3

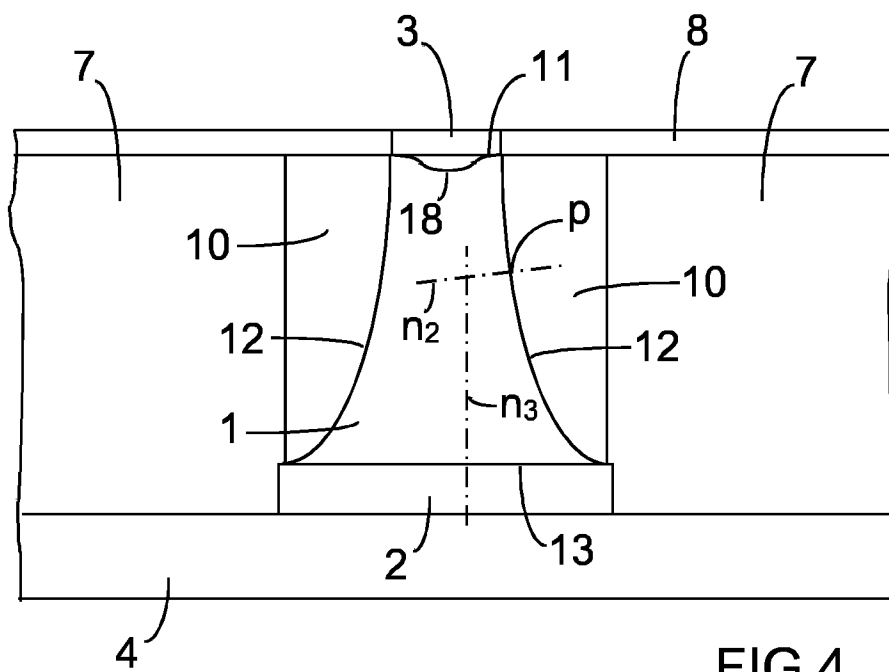


FIG 4

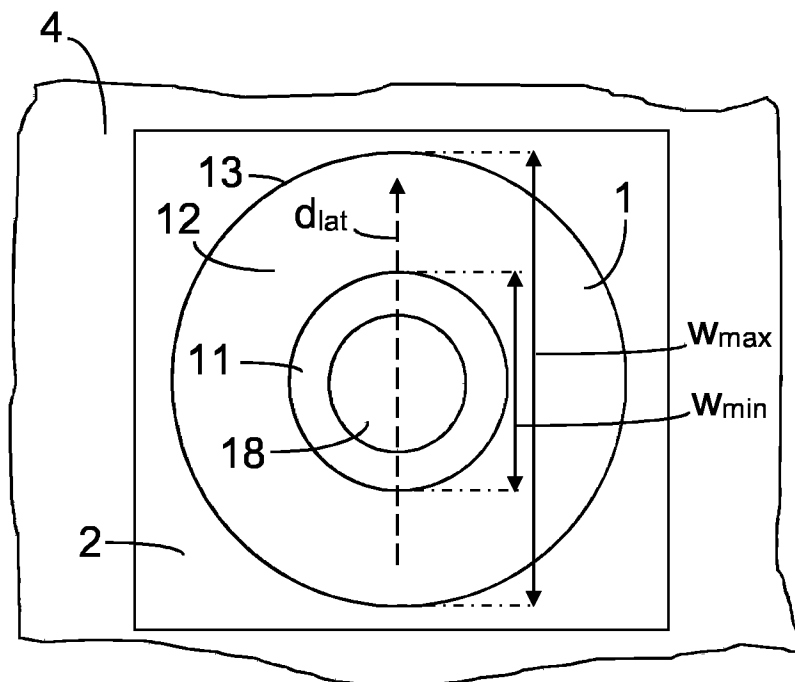
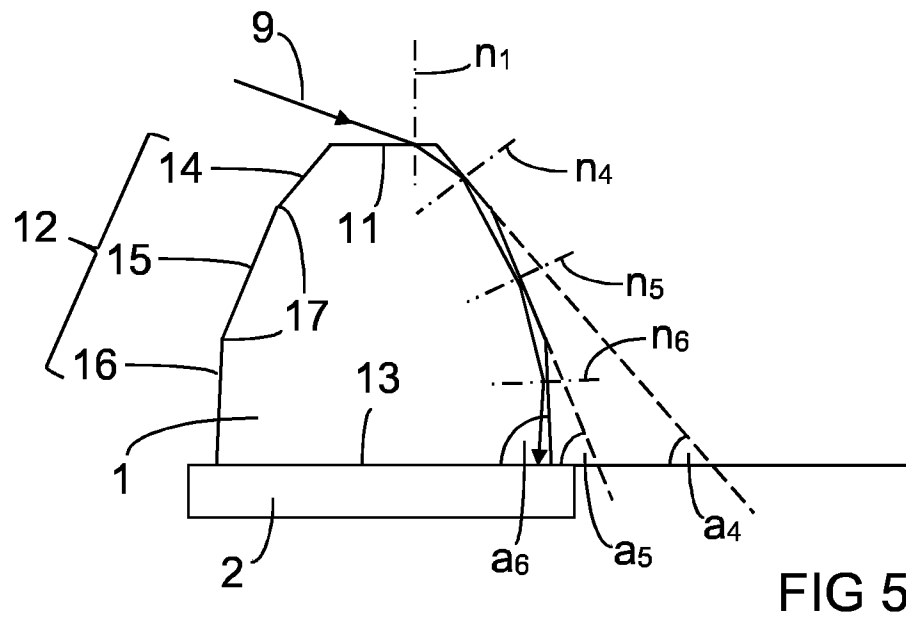


FIG 6

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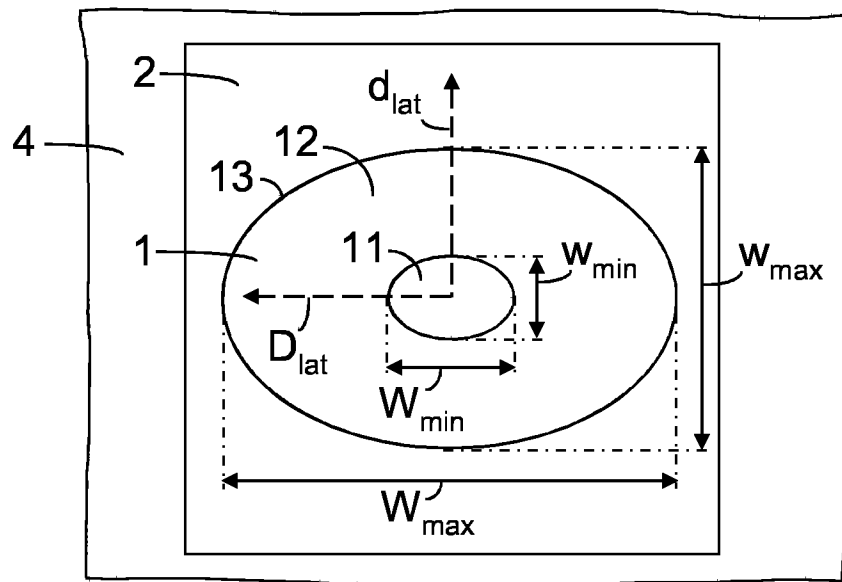


FIG 7

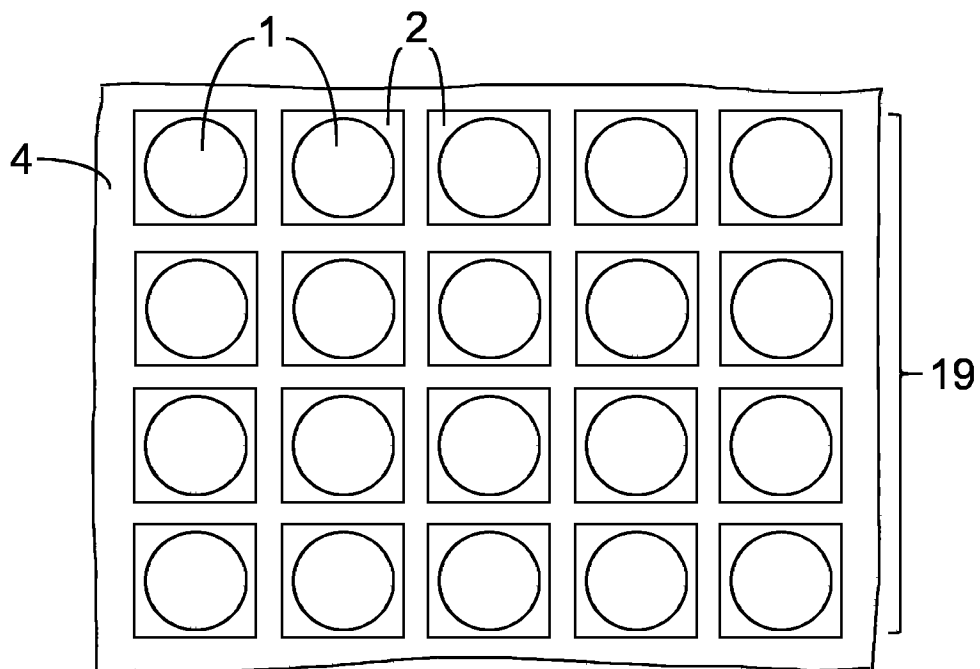


FIG 8

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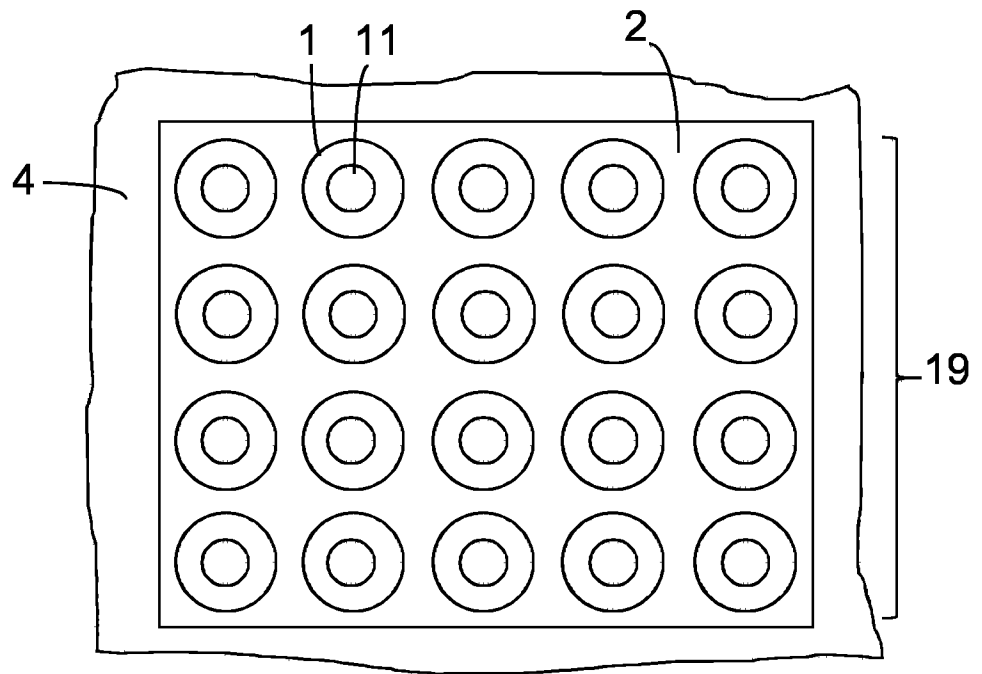


FIG 9

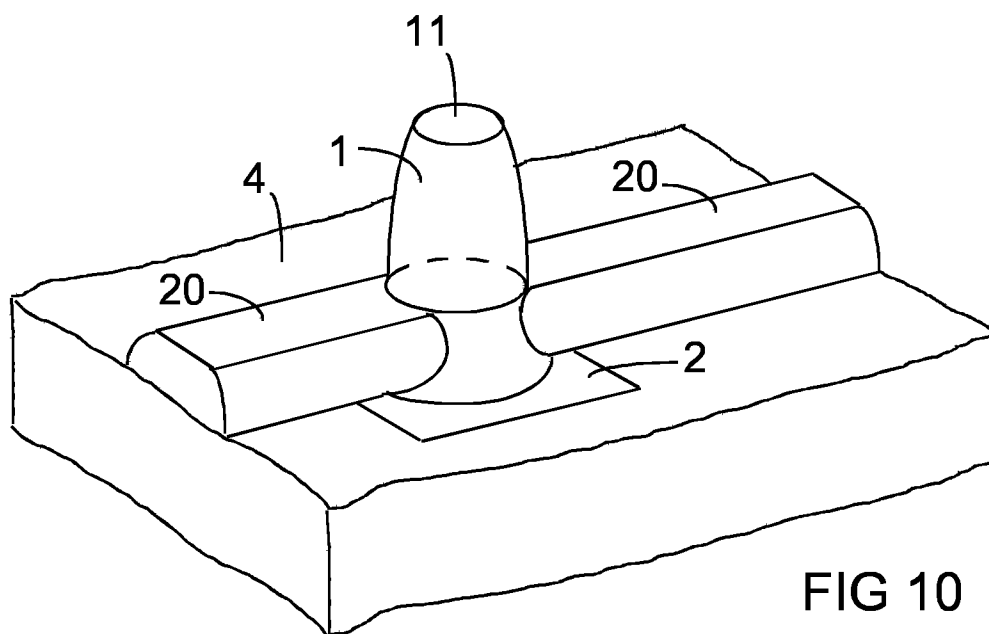


FIG 10

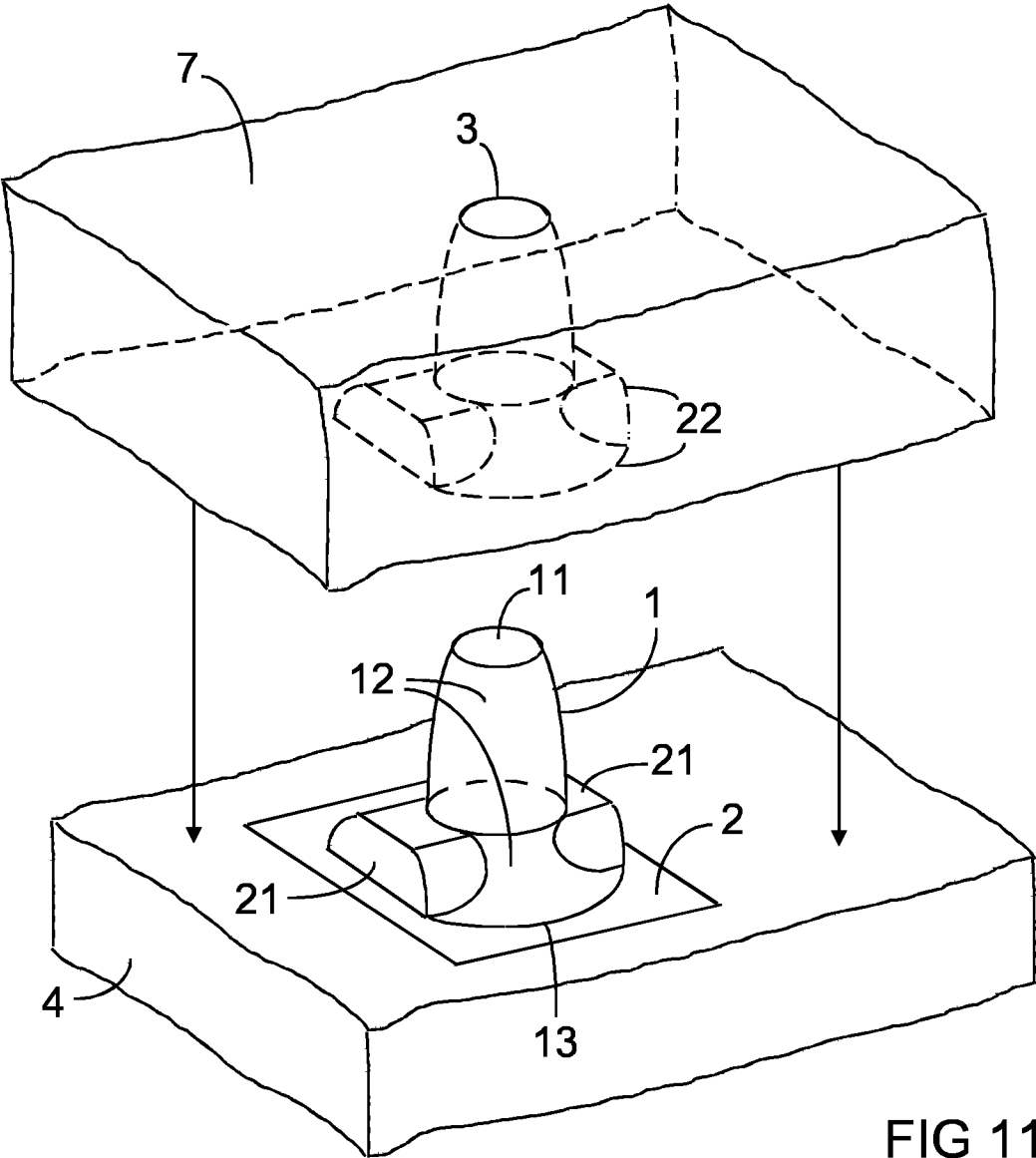


FIG 11

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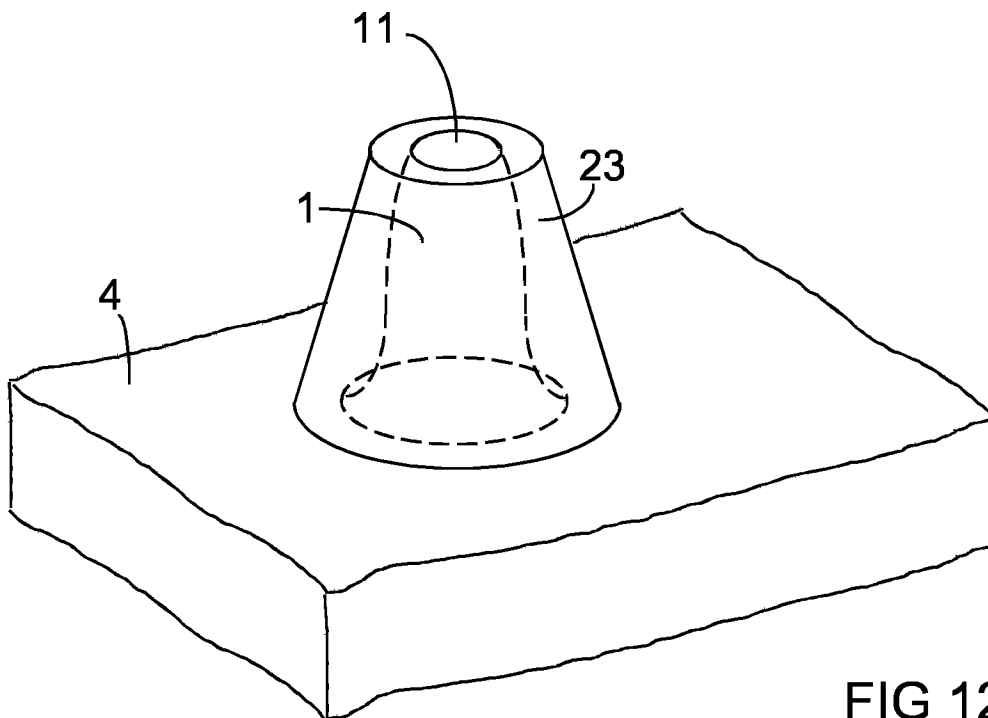


FIG 12

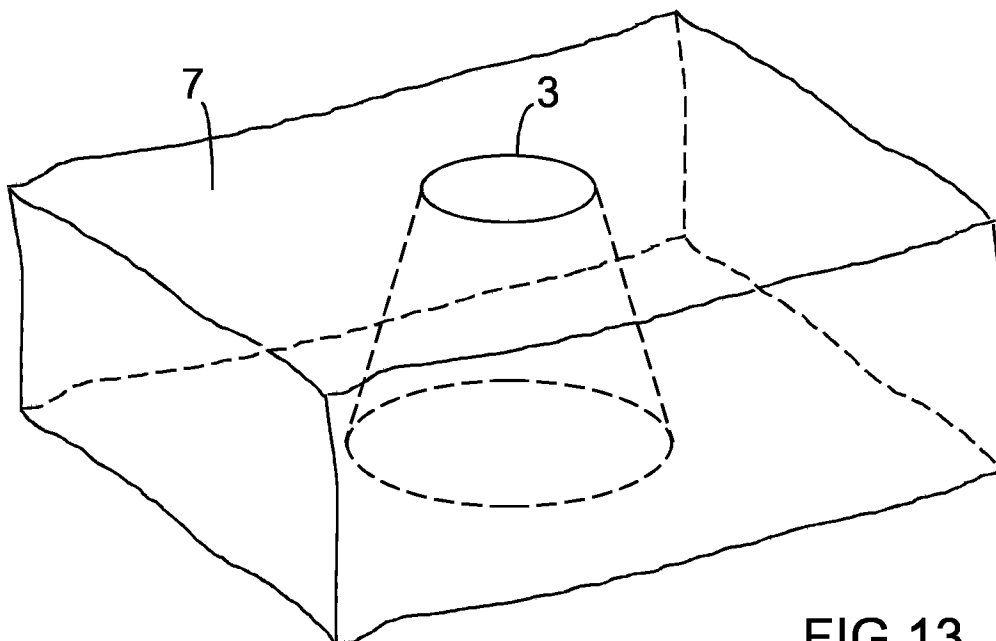


FIG 13

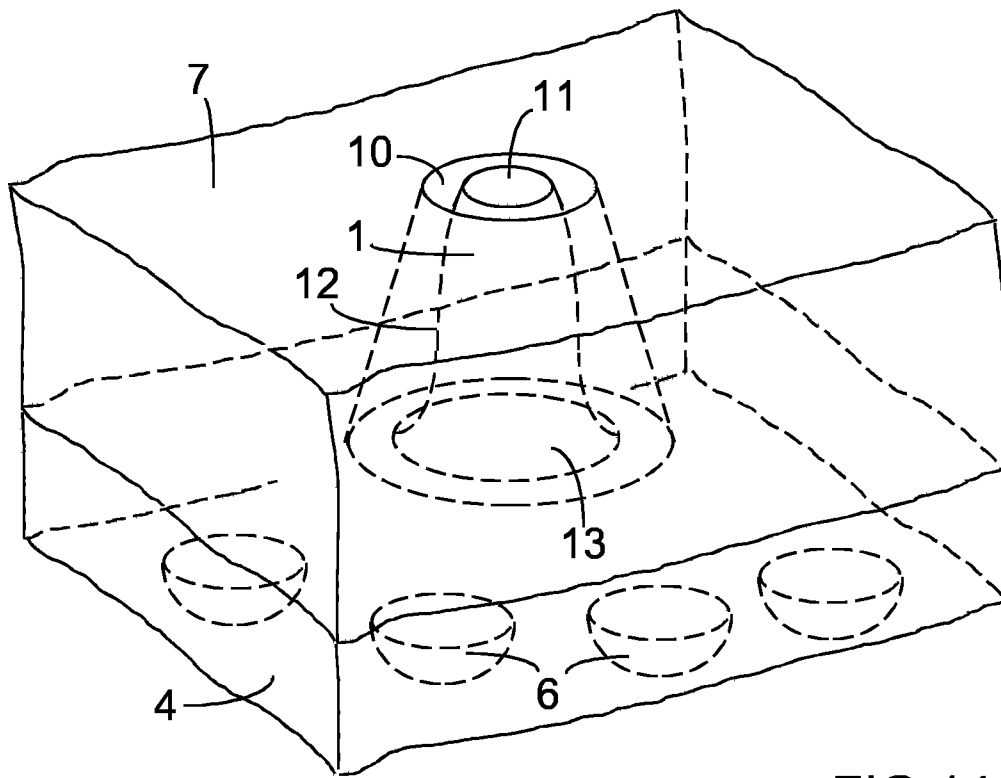


FIG 14

INTERNATIONAL SEARCH REPORT

International application No
PCT/EP2015/061723

A. CLASSIFICATION OF SUBJECT MATTER
INV. G02B19/00 G01J1/42 G01J1/04
ADD.

According to International Patent Classification (IPC) or to both national classification and IPC

B. FIELDS SEARCHED

Minimum documentation searched (classification system followed by classification symbols)
G02B G01J

Documentation searched other than minimum documentation to the extent that such documents are included in the fields searched

Electronic data base consulted during the international search (name of data base and, where practicable, search terms used)

EPO-Internal

C. DOCUMENTS CONSIDERED TO BE RELEVANT

Category*	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
X Y	FR 2 887 627 A1 (SAGEM DEFENSE SECURITE [FR]) 29 December 2006 (2006-12-29) page 8, line 32 - page 9, line 1 page 10, line 1 - line 7 page 10, line 28 - page 11, line 2 page 11, line 14 - line 17 figures 4,11 -----	1-3,5,7, 9,12 4,6, 13-15
X	WO 96/31742 A1 (TIR TECHNOLOGIES INC [US]) 10 October 1996 (1996-10-10) page 14, line 26 - line 31 abstract figure 1 -----	1,8-11
X	US 2012/037205 A1 (TADAYON SAIED [US] ET AL) 16 February 2012 (2012-02-16) abstract figures 1(a), 1(b),2,4(a) ----- -/-	1,9

☒ Further documents are listed in the continuation of Box C.

☒ See patent family annex.

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Date of the actual completion of the international search

20 July 2015

Date of mailing of the international search report

28/07/2015

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Authorized officer

Denise, Christophe

INTERNATIONAL SEARCH REPORT

International application No

PCT/EP2015/061723

C(Continuation). DOCUMENTS CONSIDERED TO BE RELEVANT

Category*	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
X	US 2012/037793 A1 (ONG CHI BOON [SG] ET AL) 16 February 2012 (2012-02-16) abstract figure 5	1,2,9
Y	----- US 2014/145069 A1 (EARMAN ALLEN M [US] ET AL) 29 May 2014 (2014-05-29) figure 3F -----	4,6, 13-15

INTERNATIONAL SEARCH REPORT

Information on patent family members

International application No

PCT/EP2015/061723

Patent document cited in search report	Publication date	Patent family member(s)	Publication date
FR 2887627	A1	29-12-2006	FR 2887627 A1
			WO 2007003729 A1
			29-12-2006
			11-01-2007
WO 9631742	A1	10-10-1996	AU 5530296 A
			CN 1181131 A
			EP 0840875 A1
			JP H11504124 A
			US 5676453 A
			WO 9631742 A1
			23-10-1996
			06-05-1998
			13-05-1998
			06-04-1999
			14-10-1997
			10-10-1996
US 2012037205	A1	16-02-2012	NONE
US 2012037793	A1	16-02-2012	NONE
US 2014145069	A1	29-05-2014	CN 103852160 A
			TW 201421708 A
			US 2014145069 A1
			11-06-2014
			01-06-2014
			29-05-2014